

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	ISC010N06NM5	**Issued**	08. April 2022
MA#	MA005710659		
Package	PG-TSON-8-3	**Weight***	123.74 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.270	1.83	1.83	18343	18343
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		73	
	non noble metal	zinc	7440-66-6	0.036	0.03		293	
	non noble metal	iron	7439-89-6	0.725	0.59		5859	
	non noble metal	copper	7440-50-8	29.440	23.79	24.42	237918	244143
wire	noble metal	gold	7440-57-5	0.053	0.04	0.04	430	430
encapsulation	organic material	carbon black	1333-86-4	0.094	0.08		759	
	plastics	epoxy resin	-	4.838	3.91		39094	
	inorganic material	silicondioxide	60676-86-0	42.035	33.96	37.95	339701	379554
leadfinish	non noble metal	tin	7440-31-5	1.343	1.09	1.09	10851	10851
plating	noble metal	silver	7440-22-4	0.030	0.02	0.02	245	245
solder	non noble metal	tin	7440-31-5	0.061	0.05		496	
	noble metal	silver	7440-22-4	0.077	0.06		620	
	non noble metal	lead	7439-92-1	2.931	2.37	2.48	23690	24806
heat sink clip	inorganic material	phosphorus	7723-14-0	0.009	0.01		77	
	non noble metal	iron	7439-89-6	0.032	0.03		255	
	non noble metal	copper	7440-50-8	31.570	25.51	25.55	255133	255465
heatspreader	inorganic material	phosphorus	7723-14-0	0.002			20	
	non noble metal	zinc	7440-66-6	0.010	0.01		79	
	non noble metal	iron	7439-89-6	0.196	0.16		1588	
	non noble metal	copper	7440-50-8	7.978	6.45	6.62	64476	66163
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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